Filename: BOM-PMP8677_RevB Project(001).xls
Variant: 001

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1	1	22uF	CAP, AL, 22uF, 400V, +/-20%, 1.302176 ohm, TH	12.5x25	EEUED2G220	Panasonic
C2, C3	2	0.15uF	CAP, Film, 0.15uF, 630V, +/-10%, TH	B32922_12mm	B32922C3154K	EPCOS Inc
C4	1	3300pF	CAP, CERM, 3300pF, 630V, X7R, xx%, [PackageReference]	1206	Used in BOM report	Used in BOM report
C5	1	470uF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	RNU1C471MDN1PH	Used in BOM report
C6	1	DNP	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	Used in BOM report	Used in BOM report
C7	1	1uF	CAP, CERM, xxxF, 16V, X7R	0805	Used in BOM report	Used in BOM report
C8, C9	2	10uF	CAP, CERM, xxxF, 16V, [TempCo], xx%, [PackageReference]	1210	Used in BOM report	Used in BOM report
C10	1	22uF	CAP, AL, 22uF, 25V, +/-20%, 1 ohm, SMD	SMT Radial D	EEE-FC1E220P	Panasonic
C11	1	2.2uF	CAP, CERM, xxxF, 25V, X7R	0805	Used in BOM report	Used in BOM report
C12	1	1nF	CAP, CERM, xxxF, 100V, [TempCo], xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C13	1	100pF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C14	1	0.01uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C15	1	49.9k	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C16	1	100pF	CAP, CERM, xxxF, 50V, X7R xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C17	1	0.022uF	CAP, CERM, xxxF, 50V, X7R, xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C18	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C19, C20	2	3300pF	Capacitor, Ceramic Disk, 220V	0.394 X 0.315 inch Max.	ECKANA332ME	Panasonic
D1	1	DF06S	Diode, Switching-Bridge, 600V, 1A, DF-S	DF-S	DF06S-E3	Vishay-Semiconductor
D2	1	MURS160	Diode, [Type], xxxV, x.xxA, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
D3	1		Diode, P-N, 120V, SOT-23	SOT-23	BAS19	Micro Commercial Component
D4	1	DNP	DIODE ZENER 15V 500MW SOD-123	SOD123	MMSZ5245BT	On Semi
F1	1	1A	Fuse, Slow Blow, 1A	0.335 inch	37211000001	Wickmann
L1	1	DNP	Coupled inductor, 600uH, 1A, 0.2 ohm, TH	Coupled inductor, 17.5x17x11mm	UU9.8V-601LF	GCI Technologies
L2	1	10mH	Coupled inductor, 10mH, 1A	17.5x22x13 mm	744822110	Wurth Elektronik eiSos
Q1	1	BSS126	MOSFET, Nch, 600V, 7 mA, 700 Ohm	SOT23	BSS126	Infineon
Q2	1	CSD18533Q5A	MOSFET, N-Chan, 60V, 18A, 6.1 mOhm	QFN-8 POWER	CSD18533Q5A	TI
Q3	1	650V	MOSFET, N-CH, 650V	DDPAK	SPB04N60C3	Infineon Technologies
R1, R4	2	10k	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R2	1	150	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R3	1	100k	RES, xxx ohm, x%, xW, [PackageReference]	2010	Used in BOM report	Used in BOM report
R5, R11, R14	3	0	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R6	1	2M	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R7	1	49.9	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R8	1	0	RES, xxx ohm, x%, xW, [PackageReference]	0805	Used in BOM report	Used in BOM report
R9	1	1k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R10	1	10	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R12	1	31.6k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R13	1	49.9	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R15	1	4.99k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R16, R22	2	11.5k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R17, R21	2	DNP	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R18	1	100k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R19	1	0.22	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R20	1	15k	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
RS1	1	DNP	Thermistor,	0.590 x 0.276 inch	B57237xxxxxM000	Epcos
RV1	1	DNP	Varistor, Disk, 350V, 1W, TA @ 85C°	D Size	SIOV-S20K275	Epcos
T1	1	800uH	Transformer, 800uH, TH	32.25x22.96x27.05mm	750815330_01	Wurth Elektronik eiSos
TP1	1	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone
TP2	1	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone
TP3, TP4	2	Double	Terminal, Turret, TH, Double	Keystone1503-2	1503-2	Keystone
TP5, TP6	2	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP7	1	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1		IC, Synchronous Rectifier Controller, TSOP-6	TSOP-6	TEA1792TS	NXP Semiconductor
U2	1	LM5023	IC, AC-DC Quasi-Resonant Current Mode PWM Controller	MSOP	LM5023MM	National Semi
U3	1	FOD817A	IC, Optocoupler, xx-V, yy% CTR	SMT-4PDIP	FOD817xx	Fairchild

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
U4	1		Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT-23, Pb-Free	MF03A	LMV431AIMFX/NOPB	National Semiconductor

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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